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Part Number:

0737690100

Status:

Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Stacking Header, High Rise Vertical, Press-Fit, Open End Option, 72 Circuits, Stack Height 15.05mm

Documents:

- 3D Model

Product Specification PS-73780-999-001 (PDF)
- Drawing (PDF)

Packaging Specification PK-70873-0870-001 (PDF)
- 3D Model (PDF)

RoHS Certificate of Compliance (PDF)

General

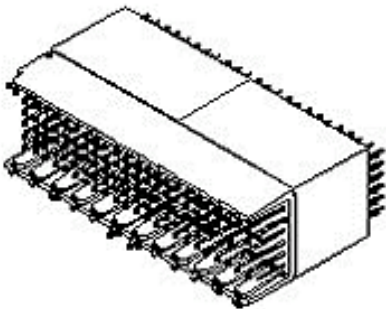
Product Family	Backplane Connectors
Series	73769
Application	Backplane, Mezzanine
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800753948020

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	12.780/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
D(2020)9139-DC (19
Jan 2021)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73769 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Backplane Signal Insertion Module Press-In Tool for 2.00mm Pitch HDM* Board-to-Board Backplane Header	622008502

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0870-001
Product Specification	PS-73780-999-001
Sales Drawing	SD-73769-001-001

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